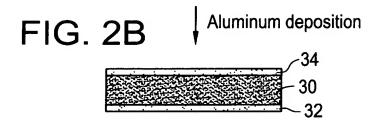
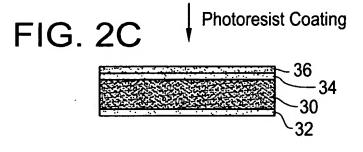
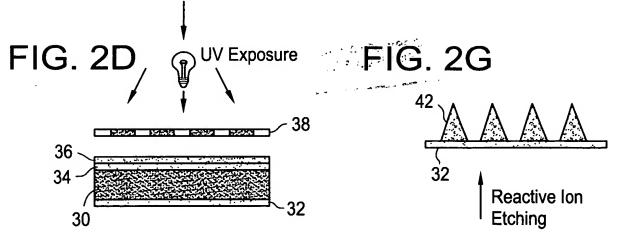


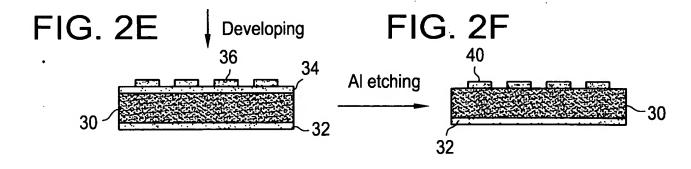
FIG. 2A











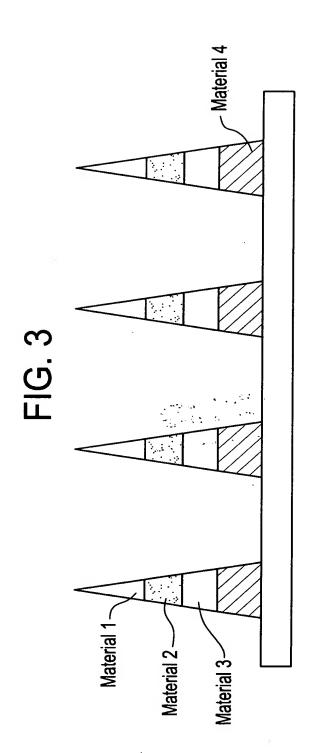
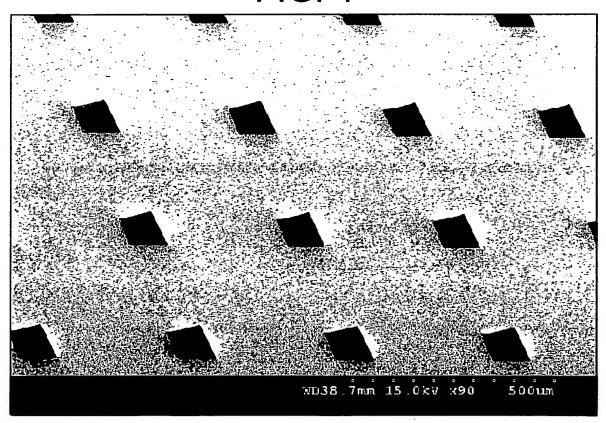


FIG. 4



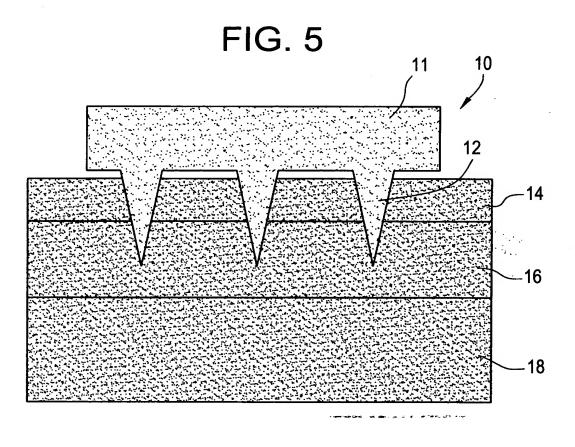
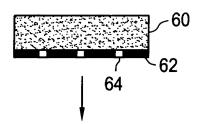
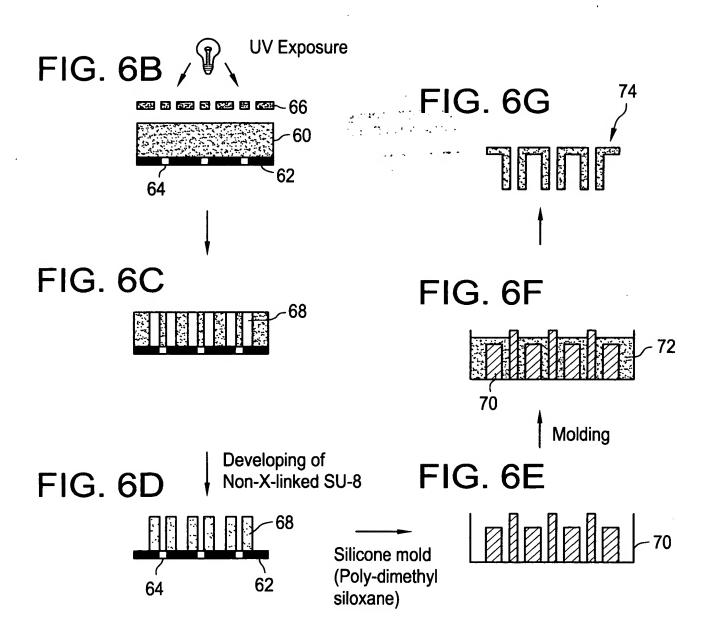
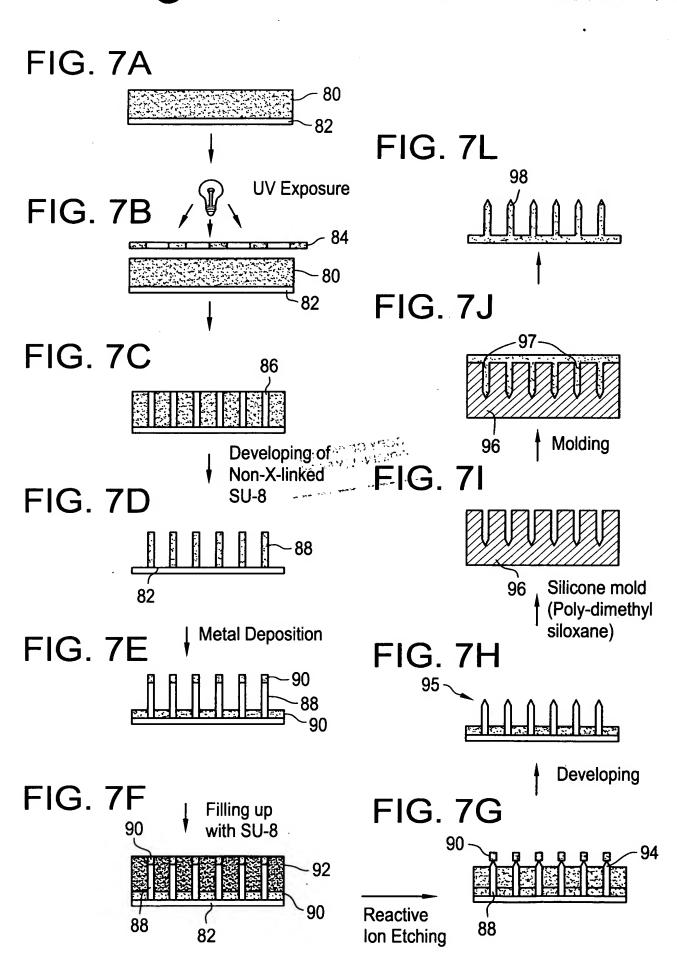
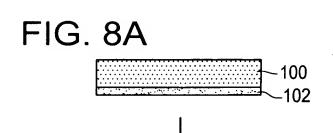


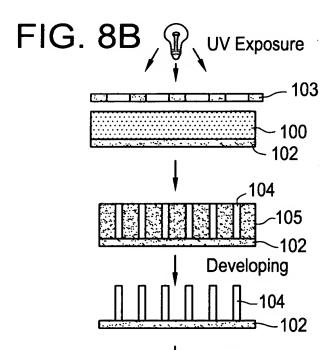
FIG. 6A

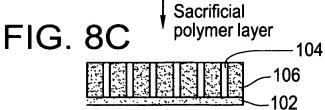


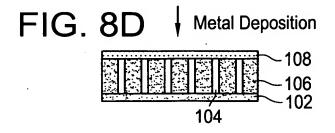


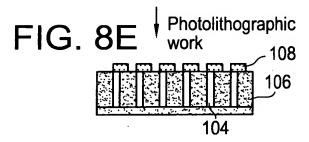


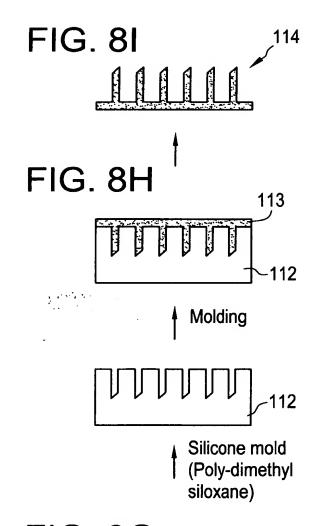












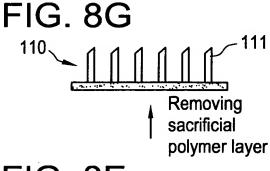




FIG. 9

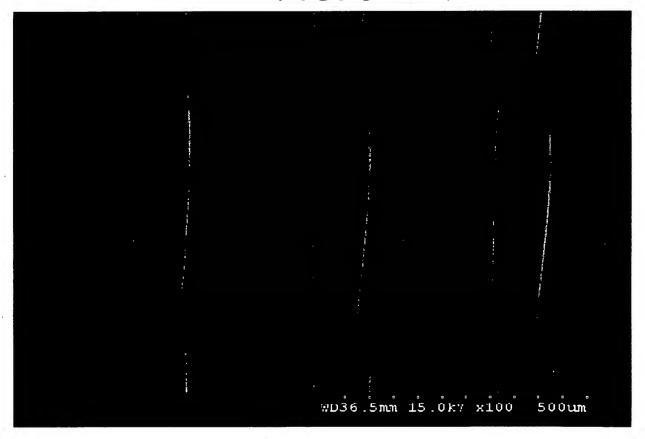


FIG. 10A

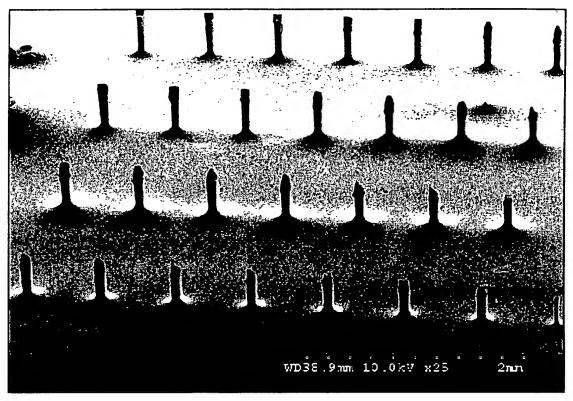
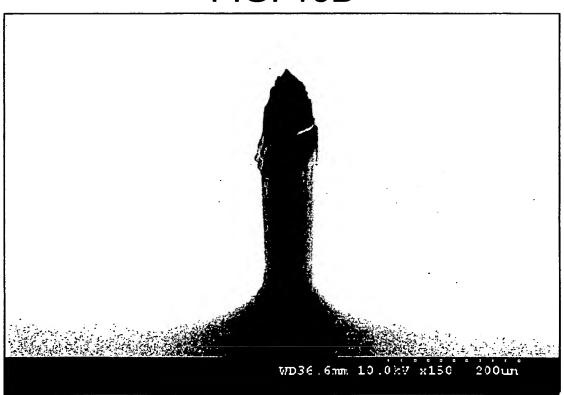


FIG. 10B



UIS & H 10/023-259 FILL Decen LCC 14

FIG. 11A

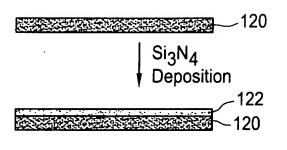


FIG. 11B Photolithographic work + Reactive ion etching

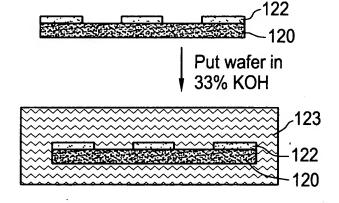
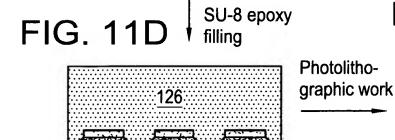


FIG. 11C KOH wet etching

124
122
120

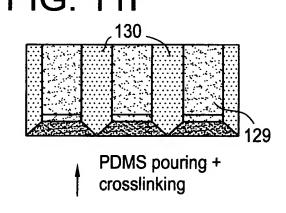


122

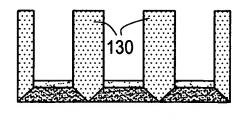
120

FIG. 11G 132

FIG. 11F



Reactive ion etching



Developing

FIG. 11E

